



Click [here](#) for the 3D model.

General Information

Series	KONNEKT Comm COG
Style	KONNEKT
Description	SMD, MLCC, KONNEKT, Ultra-Stable, Class I
Features	High Density Packaging
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	650 mg
Chip Size	2220-2
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.2 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	945 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 PPM/C
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	500 MOhms

Dimensions

L	5.7mm +/-0.4mm
W	5mm +/-0.4mm
T	5.1mm +/-0.4mm
B	0.6mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	300

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.